

IN THE CLAIMS:

Please cancel claim 2, and amend claim 2 as follows:

Claim 1. (cancelled)

Claim 2. (currently amended) A high-frequency multilayer circuit substrate comprising:

a plurality of circuit layers;

a via hole penetrating the plurality of circuit layers to be connected to each other;

a via hole metal pad provided around the via hole;

a planar impedance matching circuit connected to the via hole through the via hole metal pad; and

a signal transmission line connected to the planar impedance matching circuit, wherein

a characteristic impedance of a via hole connecting portion formed by the via hole, the via hole metal pad and the planar impedance matching circuit matches a characteristic impedance of the signal transmission line,

the planar impedance matching circuit ~~is formed by~~ includes an impedance matching transmission line, one end of which is connected to the via hole through the via hole metal pad and other end of which is directly connected to the signal transmission line, the via hole metal pad, the planar impedance matching circuit and the signal transmission line being located on the same circuit layer.

Claim 3. (previously amended) A high-frequency multilayer circuit substrate as set forth in claim 2, wherein

the characteristic impedance of the via hole connecting portion matches the characteristic impedance of the signal transmission line based on an adjusted width and length of the impedance matching transmission line.

Claim 4. (previously amended) A high-frequency multilayer circuit substrate as set forth in claim 2, wherein

the planar impedance matching circuit is formed by the impedance matching transmission line and stubs which are connected to both sides of the impedance matching transmission line at the other end connected to the signal transmission line.

Claim 5. (previously amended) A high-frequency multilayer circuit substrate as set forth in claim 4, wherein

the characteristic impedance of the via hole connecting portion matches the characteristic impedance of the signal transmission line based on an adjusted width and length of the impedance matching transmission line and a width and a length of each of the stubs.

Claim 6. (previously amended) A high-frequency multilayer circuit substrate as set forth in claim 2, wherein

the planar impedance matching circuit is formed by a plurality of impedance matching transmission lines having at least two different widths and connected in series to the via hole and the signal transmission line.

Claim 7. (previously amended) A high-frequency multilayer circuit substrate as set forth in claim 6, wherein

the characteristic impedance of the via hole connecting portion matches the characteristic impedance of the signal transmission line based on adjusted widths and lengths of the impedance matching transmission lines.